MATERIAL DECLARATION SHEET



Material Number	CD1408 Serial				
Product Line	Semiconductor Products				
Compliance Date	2006/9/12				
RoHS Compliant	Yes	MSL	1		



No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	FRP	Others	6	Continuous filament glass fibers	65997-17-3	43	21.5	50.0
				Copper foil	7440-50-8	14	7	
				Non-Hazardous cured resin	Proprietary	43	21.5	
2	Ероху	Plastic	3.54	Silicon Dioxides	7631-86-9	55	16.225	29.5
				P-F-R Resin	9003-36-5	45	13.275	
3	Solder Cream	Metal	0.17	Lead *2	7439-92-1	88	1.247	1.4
				Tin	7440-31-5	10	0.142	
				Silver	7440-22-4	2	0.028	
4	Dice	Others	2.05	Silicon	7440-21-3	35.77	6.11	17.1
				Nickel	7440-02-0	0.7	0.12	
				Lead ^{*3}	7439-92-1	63.51	10.85	
				Gold	7440-57-5	0.02	0.003	
5	Terminal Plating	Metal	0.24	Tin	7440-31-5	>99.9	2	2.0
- 		Total weight	12					

This Document was updated on: 2015/05/05

Important remarks:

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- 1. It is the responsibility of the user to verify they are accessing the latest version.
- 2. * : Excepted for RoHS 7(a)-Lead in high melting temperature type solders (i.e. lead- based alloys containing 85% by weight or more lead);
- 3. Excepted for RoHS 7(c) I-Electrical and electronic components containing lead in a glass or ceramic other then dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound;